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Intel - EPM7256BTC144-10 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

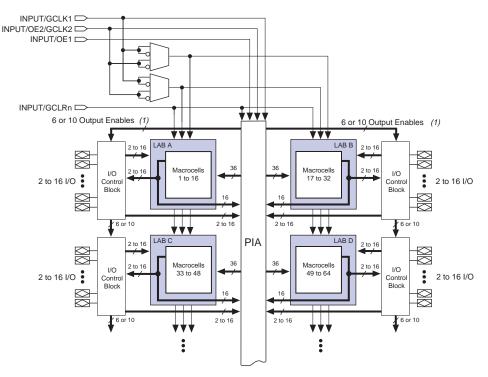
Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	120
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256btc144-10

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong





Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enables. EPM7512B devices have ten output enables.

Logic Array Blocks

The MAX 7000B device architecture is based on the linking of high-performance LABs. LABs consist of 16 macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- **3**6 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the MAX+PLUS II software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

Two global clock signals are available in MAX 7000B devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000B device may be set to either a high or low state. This power-up state is specified at design entry.

All MAX 7000B I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast input setup time. The input path from the I/O pin to the register has a programmable delay element that can be selected to either guarantee zero hold time or to get the fastest possible set-up time (as fast as 1.0 ns).

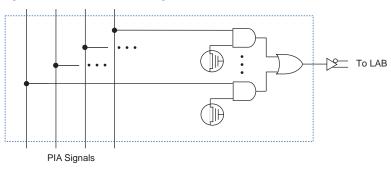


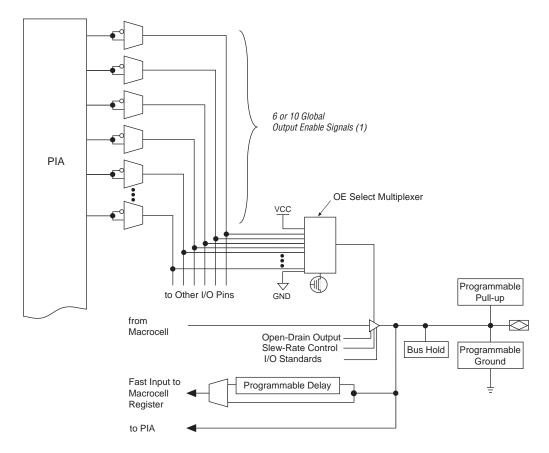
Figure 5. MAX 7000B PIA Routing

While the routing delays of channel-based routing schemes in masked or field-programmable gate arrays (FPGAs) are cumulative, variable, and path-dependent, the MAX 7000B PIA has a predictable delay. The PIA makes a design's timing performance easy to predict.

I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC} . Figure 6 shows the I/O control block for MAX 7000B devices. The I/O control block has six or ten global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.





Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enable signals. EPM7512B devices have ten output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to $V_{CC'}$, the output is enabled.

The MAX 7000B architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

MAX 7000B devices contain two I/O banks. Both banks support all standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Within a bank, any one of the terminated standards can be supported.

Figure 9 shows the arrangement of the MAX 7000B I/O banks.

Programmable I/O Banks

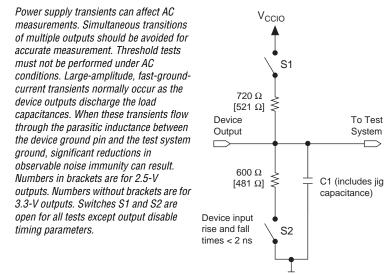
Figure 9. MAX 7000B I/O Banks for Various Advanced I/O Standards

Table 11 shows which macrocells have pins in each I/O bank.

Table 11. Macrocell Pins Co	ntained in Each I/O Bank	
Device	Bank 1	Bank 2
EPM7032B	1-16	17-32
EPM7064B	1-32	33-64
EPM7128B	1-64	65-128
EPM7256B	1-128, 177-181	129-176, 182-256
EPM7512B	1-265	266-512

Each MAX 7000B device has two VREF pins. Each can be set to a separate V_{REF} level. Any I/O pin that uses one of the voltage-referenced standards (GTL+, SSTL-2, or SSTL-3) may use either of the two VREF pins. If these pins are not required as VREF pins, they may be individually programmed to function as user I/O pins.

Figure 11. MAX 7000B AC Test Conditions



Operating Conditions

Tables 14 through 17 provide information on absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for MAX 7000B devices.

Table 1	4. MAX 7000B Device Absol	ute Maximum Ratings Note (1)			
Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage		-0.5	3.6	V
V _{CCIO}	Supply voltage		-0.5	3.6	V
VI	DC input voltage	(2)	-2.0	4.6	V
I _{OUT}	DC output current, per pin		-33	50	mA
T _{STG}	Storage temperature	No bias	-65	150	°C
T _A	Ambient temperature	Under bias	-65	135	°C
TJ	Junction temperature	Under bias	-65	135	°C

Table 1	7. MAX 7000B Device Capacital	nce Note (9)				
Symbol						
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		8	pF	
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		8	pF	

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 4.6 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) All pins, including dedicated inputs, I/O pins, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- (4) These values are specified under the Recommended Operating Conditions in Table 15 on page 29.
- (5) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (6) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL or CMOS output current.
- (7) This value is specified for normal device operation. During power-up, the maximum leakage current is $\pm 300 \,\mu$ A.
- (8) This pull-up exists while devices are being programmed in-system and in unprogrammed devices during power-up. The pull-up resistor is from the pins to V_{CCIO}.
- (9) Capacitance is measured at 25° C and is sample-tested only. Two of the dedicated input pins (OE1 and GCLRN) have a maximum capacitance of 15 pF.
- (10) The POR time for all 7000B devices does not exceed 100 μs. The sufficient V_{CCINT} voltage level for POR is 2.375 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (11) These devices support in-system programming for -40° to 100° C. For in-system programming support between -40° and 0° C, contact Altera Applications.

Table 20. EPM7032	Table 20. EPM7032B Selectable I/O Standard Timing Adder Delays Notes (1)										
I/O Standard	Parameter			Speed	Grade			Unit			
		-3.5 -5.0 -7.5				.5					
		Min	Max	Min	Max	Min	Max				
PCI	Input to PIA		0.0		0.0		0.0	ns			
	Input to global clock and clear		0.0		0.0		0.0	ns			
	Input to fast input register		0.0		0.0		0.0	ns			
	All outputs		0.0		0.0		0.0	ns			

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of all LABs.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPPW} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

I/O Standard	Parameter			Speed	Grade			Unit
		-	3	-	5	-	7	
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.4		0.6	ns
	Input to global clock and clear		0.3		0.4		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.7		1.1	ns
	Input to global clock and clear		0.5		0.7		1.1	ns
	Input to fast input register		0.4		0.6		0.9	ns
	All outputs		1.2		1.7		2.6	ns
SSTL-2 Class I	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		-0.1		-0.1		-0.2	ns
SSTL-3 Class I	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.6		2.3		3.4	ns
	Input to global clock and clear		1.6		2.3		3.4	ns
	Input to fast input register		1.5		2.1		3.2	ns
	All outputs		0.0		0.0		0.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	4	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		4.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		4.0		7.5		10.0	ns
t _{SU}	Global clock setup time	(2)	2.5		4.5		6.1		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		1.0		1.5		1.5		ns
t _{FH}	Global clock hold time of fast input		1.0		1.0		1.0		ns
t _{FZHSU}	Global clock setup time of fast input with zero hold time		2.0		3.0		3.0		ns
t _{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	2.8	1.0	5.7	1.0	7.5	ns
t _{CH}	Global clock high time		1.5		3.0		4.0		ns
t _{CL}	Global clock low time		1.5		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.2		2.0		2.8		ns
t _{AH}	Array clock hold time	(2)	0.2		0.7		0.9		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.1	1.0	8.2	1.0	10.8	ns
t _{ACH}	Array clock high time		1.5		3.0		4.0		ns
t _{ACL}	Array clock low time		1.5		3.0		4.0		ns
tCPPW	Minimum pulse width for clear and preset		1.5		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		4.1		7.9		10.6	ns
f _{CNT}	Maximum internal global clock frequency	(2), (3)	243.9		126.6		94.3		MHz
t _{acnt}	Minimum array clock period	(2)		4.1		7.9		10.6	ns
facnt	Maximum internal array clock frequency	(2), (3)	243.9		126.6		94.3		MHz

I/O Standard	Parameter			Speed	Grade			Unit
		-	4	-	7	-	10	
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.6		0.8	ns
	Input to global clock and clear		0.3		0.6		0.8	ns
	Input to fast input register		0.2		0.4		0.5	ns
	All outputs		0.2		0.4		0.5	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.9		1.3	ns
	Input to global clock and clear		0.5		0.9		1.3	ns
	Input to fast input register		0.4		0.8		1.0	ns
	All outputs		1.2		2.3		3.0	ns
SSTL-2 Class I	Input to PIA		1.4		2.6		3.5	ns
	Input to global clock and clear		1.2		2.3		3.0	ns
	Input to fast input register		1.0		1.9		2.5	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.4		2.6		3.5	ns
	Input to global clock and clear		1.2		2.3		3.0	ns
	Input to fast input register		1.0		1.9		2.5	ns
	All outputs		-0.1		-0.2		-0.3	ns
SSTL-3 Class I	Input to PIA		1.3		2.4		3.3	ns
	Input to global clock and clear		1.0		1.9		2.5	ns
	Input to fast input register		0.9		1.7		2.3	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.3		2.4		3.3	ns
	Input to global clock and clear		1.0		1.9		2.5	ns
	Input to fast input register		0.9	1	1.7		2.3	ns
	All outputs		0.0	1	0.0		0.0	ns
GTL+	Input to PIA		1.7		3.2		4.3	ns
	Input to global clock and clear		1.7		3.2		4.3	ns
	Input to fast input register		1.6	1	3.0		4.0	ns
	All outputs		0.0	1	0.0		0.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	5	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10.0	ns
t _{SU}	Global clock setup time	(2)	3.3		4.8		6.6		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		1.0		1.5		1.5		ns
t _{FH}	Global clock hold time for fast input		1.0		1.0		1.0		ns
t _{FZHSU}	Global clock setup time of fast input with zero hold time		2.5		3.0		3.0		ns
t _{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.3	1.0	5.1	1.0	6.7	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.4		2.0		2.8		ns
t _{AH}	Array clock hold time	(2)	0.4		0.8		1.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	5.2	1.0	7.9	1.0	10.5	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset		2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.3		7.9		10.6	ns
f _{CNT}	Maximum internal global clock frequency	(2), (3)	188.7		126.6		94.3		MHz
t _{acnt}	Minimum array clock period	(2)		5.3		7.9		10.6	ns
facnt	Maximum internal array clock frequency	(2), (3)	188.7		126.6		94.3		MHz

I/O Standard	Parameter			Speed	Grade			Unit
		-	5	-	7	-1	10	
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.4		0.6		0.8	ns
	Input to global clock and clear		0.3		0.5		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.6		0.9		1.2	ns
	Input to global clock and clear		0.6		0.9		1.2	ns
	Input to fast input register		0.5		0.8		1.0	ns
	All outputs		1.3		2.0		2.6	ns
SSTL-2 Class I	Input to PIA		1.5		2.3		3.0	ns
	Input to global clock and clear		1.3		2.0		2.6	ns
	Input to fast input register		1.1		1.7		2.2	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.5		2.3		3.0	ns
	Input to global clock and clear		1.3		2.0		2.6	ns
	Input to fast input register		1.1		1.7		2.2	ns
	All outputs		-0.1		-0.2		-0.2	ns
SSTL-3 Class I	Input to PIA		1.4		2.1		2.8	ns
	Input to global clock and clear		1.1		1.7		2.2	ns
	Input to fast input register		1.0		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.4		2.1		2.8	ns
	Input to global clock and clear		1.1		1.7		2.2	ns
	Input to fast input register		1.0		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.8	l	2.7		3.6	ns
	Input to global clock and clear		1.8	l	2.7		3.6	ns
	Input to fast input register		1.7		2.6		3.4	ns
	All outputs		0.0	1	0.0		0.0	ns

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) Note (1)										
I/O Standard	Parameter	Speed Grade								
		-5 -7 -10		0	1					
		Min	Max	Min	Max	Min	Мах			
PCI	Input to PIA		0.0		0.0		0.0	ns		
	Input to global clock and clear		0.0		0.0		0.0	ns		
	Input to fast input register		0.0		0.0		0.0	ns		
	All outputs		0.0		0.0		0.0	ns		

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPPW} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

I/O Standard	Parameter			Speed	Grade			Unit
		-	5	-	7	-1	10	
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.4		0.5		0.7	ns
	Input to global clock and clear		0.3		0.4		0.5	ns
	Input to fast input register		0.2		0.3		0.3	ns
	All outputs		0.2		0.3		0.3	ns
1.8 V TTL/CMOS	Input to PIA		0.7		1.0		1.3	ns
	Input to global clock and clear		0.6		0.8		1.0	ns
	Input to fast input register		0.5		0.6		0.8	ns
	All outputs		1.3		1.8		2.3	ns
SSTL-2 Class I	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		-0.1		-0.1		-0.2	ns
SSTL-3 Class I	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.8		2.5		3.3	ns
	Input to global clock and clear		1.9		2.6		3.5	ns
	Input to fast input register		1.8		2.5		3.3	ns
	All outputs		0.0		0.0		0.0	ns

Table 32. EPM7512B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) Note (1)										
I/O Standard	Parameter	Speed Grade					Unit			
		-5		-7		-10				
		Min	Max	Min	Max	Min	Max			
PCI	Input to PIA		0.0		0.0		0.0	ns		
	Input to global clock and clear		0.0		0.0		0.0	ns		
	Input to fast input register		0.0		0.0		0.0	ns		
	All outputs		0.0		0.0		0.0	ns		

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.12 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{ACL} , t_{CPPW} , t_{EN} , and t_{SEXP} parameters for macrocells running in low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} , in MHz) for MAX 7000B devices is calculated with the following equation:

 $P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I_{CCINT} value depends on the switching frequency and the application logic. The I_{CCINT} value is calculated with the following equation:

 $I_{CCINT} =$

 $(A \times MC_{TON}) + [B \times (MC_{DEV} - MC_{TON})] + (C \times MC_{USED} \times f_{MAX} \times tog_{LC})$

The parameters in this equation are:

MC _{TON}	=	Number of macrocells with the Turbo Bit TM option turned
		on, as reported in the MAX+PLUS II Report File (.rpt)
MC _{DEV}	=	Number of macrocells in the device
MC _{USED}	=	Total number of macrocells in the design, as reported in
		the Report File
f _{MAX}	=	Highest clock frequency to the device
tog _{LC}	=	Average percentage of logic cells toggling at each clock
- 20		(typically 12.5%)
A, B, C	=	Constants, shown in Table 33

Table 33. MAX 7000B I _{CC} Equation Constants									
Device	Α	В	C						
EPM7032B	0.91	0.54	0.010						
EPM7064B	0.91	0.54	0.012						
EPM7128B	0.91	0.54	0.016						
EPM7256B	0.91	0.54	0.017						
EPM7512B	0.91	0.54	0.019						

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

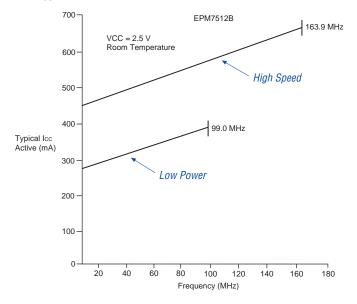


Figure 19. I_{CC} vs. Frequency for EPM7512B Devices

Figure 23. 100-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

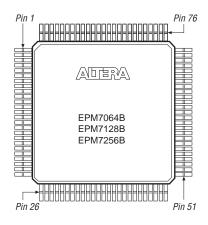


Figure 24. 100-Pin FineLine BGA Package Pin-Out Diagram

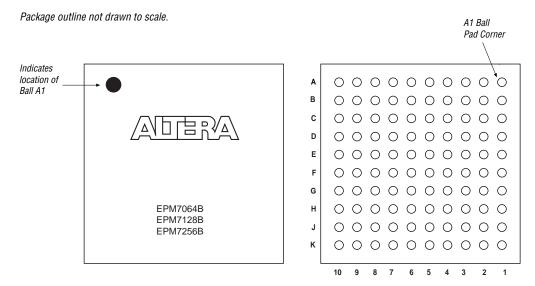


Figure 28. 256-Pin BGA Package Pin-Out Diagram

Package outline not drawn to scale.

